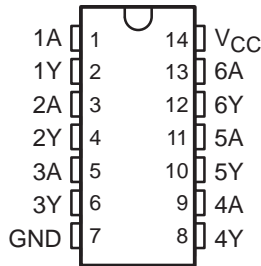


SN54HC05, SN74HC05 HEX INVERTERS WITH OPEN-DRAIN OUTPUTS

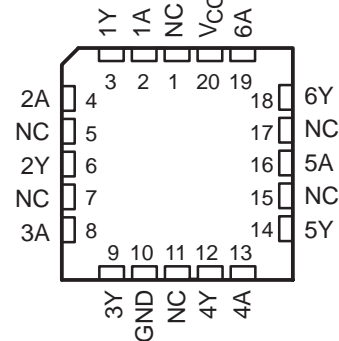
SCLS080D – MARCH 1984 – REVISED AUGUST 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20- μ A Max I_{CC}
- Typical $t_{pd} = 8$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max

SN54HC05 . . . J OR W PACKAGE
SN74HC05 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC05 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HC05 devices contain six independent inverters. They perform the Boolean function $Y = \bar{A}$ in positive logic. The open-drain outputs require pullup resistors to perform correctly. They may be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC05N	SN74HC05N
		Tube of 50	SN74HC05D	HC05
	SOIC – D	Reel of 2500	SN74HC05DR	
		Reel of 250	SN74HC05DT	
	SOP – NS	Reel of 2000	SN74HC05NSR	
	SSOP – DB	Reel of 2000	SN74HC05DBR	HC05
TSSOP – PW			Reel of 2000	SN74HC05PWR
		Reel of 250	SN74HC05PWT	
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC05J	SNJ54HC05J
	CFP – W	Tube of 150	SNJ54HC05W	SNJ54HC05W
	LCCC – FK	Tube of 55	SNJ54HC05FK	SNJ54HC05FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN54HC05, SN74HC05
HEX INVERTERS
WITH OPEN-DRAIN OUTPUTS
 SCLS080D – MARCH 1984 – REVISED AUGUST 2003

FUNCTION TABLE
 (each inverter)

INPUT A	OUTPUT Y
H	L
L	H

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54HC05			SN74HC05			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2\text{ V}$		1.5	1.5		V	
		$V_{CC} = 4.5\text{ V}$		3.15	3.15			
		$V_{CC} = 6\text{ V}$		4.2	4.2			
V_{IL}	Low-level input voltage	$V_{CC} = 2\text{ V}$			0.5	0.5	V	
		$V_{CC} = 4.5\text{ V}$			1.35	1.35		
		$V_{CC} = 6\text{ V}$			1.8	1.8		
V_I	Input voltage	0		V_{CC}	0	V_{CC}	V	
V_O	Output voltage	0		V_{CC}	0	V_{CC}	V	
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 2\text{ V}$			1000	1000	ns	
		$V_{CC} = 4.5\text{ V}$			500	500		
		$V_{CC} = 6\text{ V}$			400	400		
T_A	Operating free-air temperature	-55		125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN54HC05, SN74HC05
HEX INVERTERS
WITH OPEN-DRAIN OUTPUTS

SCLS080D – MARCH 1984 – REVISED AUGUST 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54HC05		SN74HC05		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
I _{OH}	V _I = V _{IH} or V _{IL} , V _O = V _{CC}	6 V		0.01	0.5		10		5	μA
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V	0.002	0.1		0.1		0.1	V
			4.5 V	0.001	0.1		0.1		0.1	
			6 V	0.001	0.1		0.1		0.1	
		I _{OL} = 4 mA	4.5 V	0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V	0.15	0.26		0.4		0.33	
I _I	V _I = V _{CC} or 0	6 V		±0.1	±100		±1000		±1000	nA
I _{CC}	V _I = V _{CC} or 0, I _O = 0	6 V			2		40		20	μA
C _i		2 V to 6 V		3	10		10		10	pF

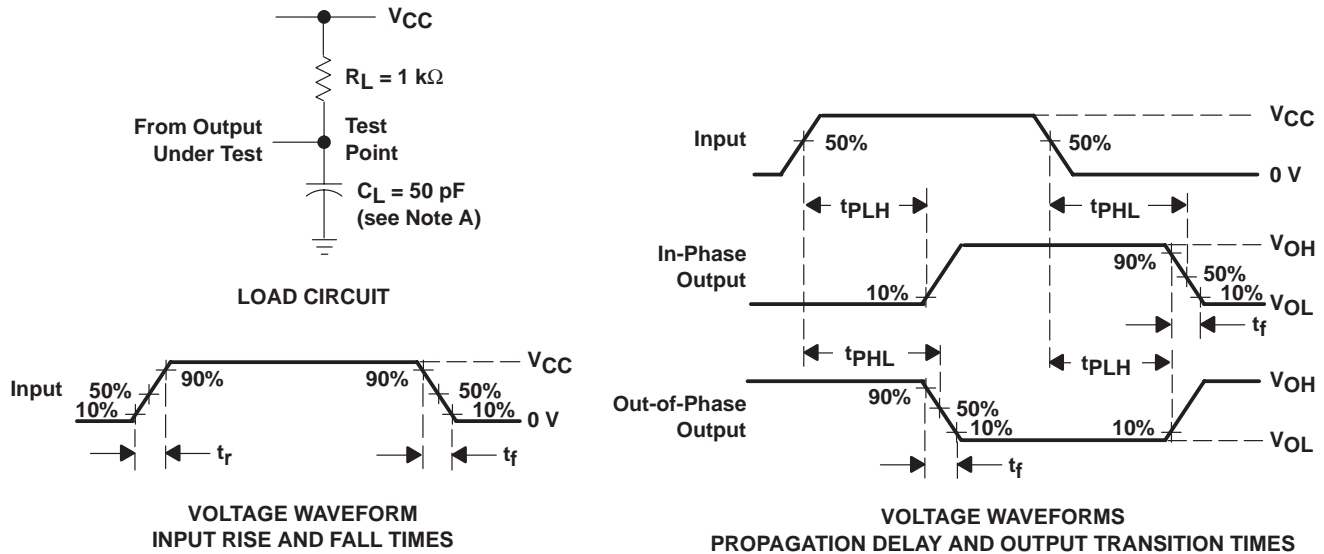
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC05		SN74HC05		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	2 V		60	115		175		145	ns
			4.5 V		13	23		35		29	
			6 V		10	20		30		25	
t _{PHL}	A	Y	2 V		45	85		130		105	ns
			4.5 V		9	17		26		21	
			6 V		8	14		22		18	
t _f		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per inverter	No load	20	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and test-fixture capacitance.
 B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r = 6\text{ ns}$, $t_f = 6\text{ ns}$.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-88718012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8871801CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
SN54HC05J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74HC05D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05DT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05DTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05DTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74HC05N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74HC05NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74HC05NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74HC05PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05PWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05PWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC05PWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54HC05FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54HC05J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54HC05, SN74HC05 :

- Catalog: [SN74HC05](#)
- Military: [SN54HC05](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC05DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC05DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC05DT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC05NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC05PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC05PWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC05DR	SOIC	D	14	2500	333.2	345.9	28.6
SN74HC05DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74HC05DT	SOIC	D	14	250	367.0	367.0	38.0
SN74HC05NSR	SO	NS	14	2000	367.0	367.0	38.0
SN74HC05PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74HC05PWT	TSSOP	PW	14	250	367.0	367.0	35.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

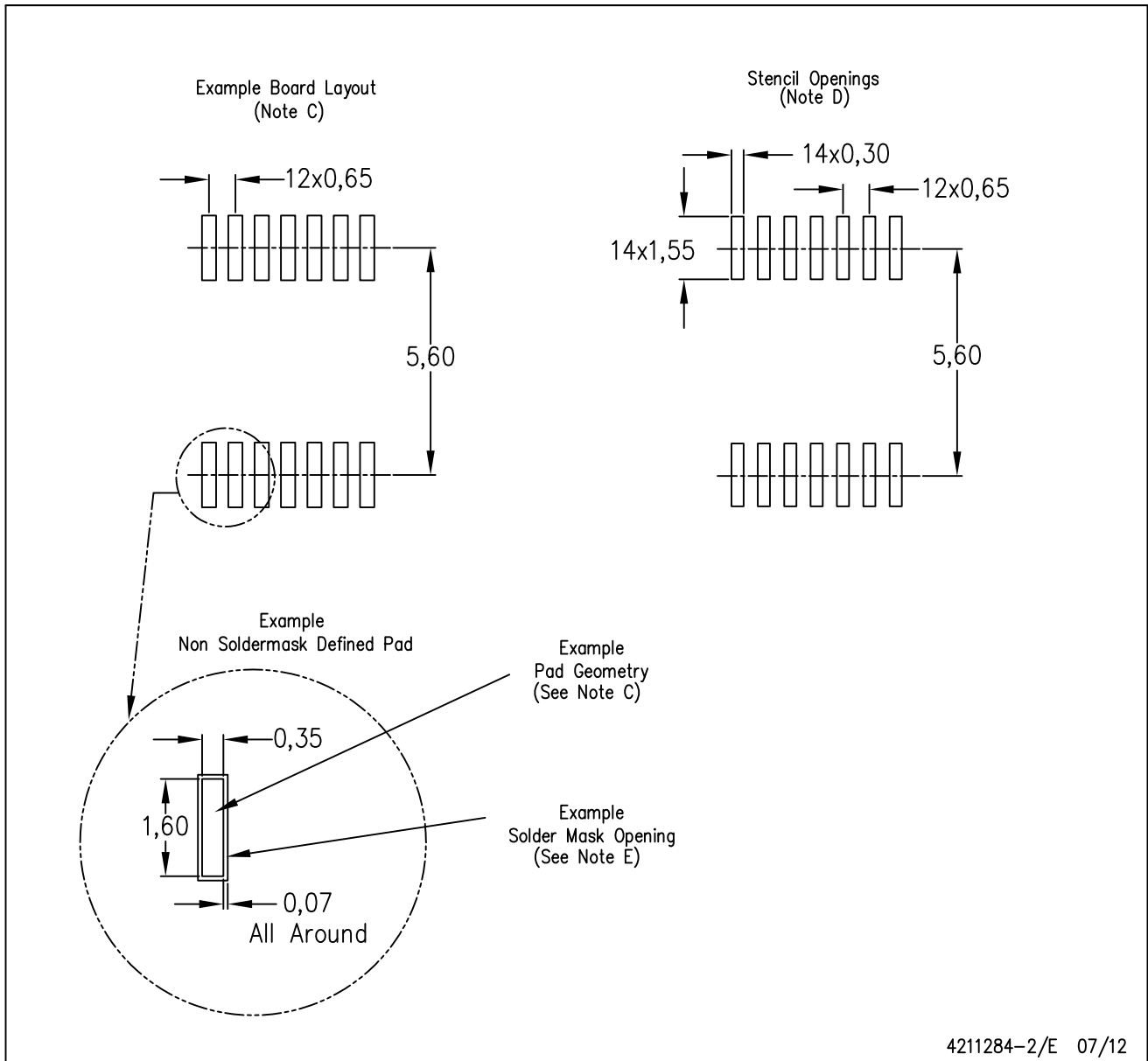


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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